



PK696 (v1.0) Jan 16, 2015

100% Material Declaration Data Sheet for Artix[®]-7 Device FB484 Package

Average Weight: 2.1679 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.237267	10.945
	Silicon	7440-21-3	100.00		0.237267	
Solder Bump					0.011261	0.519
	Tin	7440-31-5	63.00		0.007094	
	Lead	7439-92-1	37.00		0.004167	
Underfill					0.030000	1.384
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00		0.006000	
	Phenolic resin	Trade Secret	15.00		0.004500	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00		0.001500	
	Amine type accelerator	Trade Secret	5.00		0.001500	
	Silicon dioxide	60676-86-0	51.50		0.015450	
	Carbon black	1333-86-4	1.00		0.000300	
	Additives	Trade Secret	2.50		0.000750	
Solder Ball						21.250
	Tin	7440-31-5	63.00		0.460670	
	Lead	7439-92-1	37.00		0.290222	
Substrate					0.170448	65.903
	Copper	7440-50-8	36.83		1.428700	
	Tin	7440-31-5	1.11		0.526149	
	Lead	7439-92-1	0.27		0.015854	
	Silver	7440-22-4	0.02		0.003878	
	BT Core	N/A	48.18		0.000288	
	ABF	N/A	11.12		0.688304	
	Solder Mask	N/A	2.48		0.158840	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
01/16/2015	1.0	Xilinx Initial Release

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